



CRITICAL LINE WIDTH = .016 ± .001 ADJUST PROCESS TO ACHIEVE WIDTH

TABLE 1 : HOLE DIAMETERS

LETTER DESIG.	DIAMETER	QTY	TYPE	NOTES
NONE	0.010	9	PTH	+ .003 / - .003
NONE	0.018	108	PTH	+ .003 / - .003
NONE	0.043	3	PTH	+ .003 / - .003

UNLESS OTHERWISE SPECIFIED:	
DIMENSIONS ARE IN INCHES (MM)	
DRAWING PRACTICES PER MIL-STD-100	
TOLERANCES:	
.XX	+/- .01
.XXX	+/- .005
ANGLES	+/- .5 DEG

PROPRIETARY TO HITTITE MICROWAVE CORPORATION

DRAWN
DONOVAN 5/13/06

CHECKED

ENG. APPD.

HMC APPD.

RELEASED



HITTITE MICROWAVE CORPORATION
20 Alpha Road
Chelmsford, MA 01824

TITLE
PCB, EVAL
HMC575/3499LP4

SIZE	CODE ID NO.	DRAWING NO.	RI
A	1CN88	115270	
SCALE 4 TO 1	WT	SHEET 1 OF	

REVISION				
ZONE	REV	DESCRIPTION	DATE	APPROVED
	1	ENGINEERING RELEASE	5/13/06	DONOVAN

MET-1	1/2 OZ COPPER	0.062 0.067
	0.010" ± 0.001 ROGERS 4350 SEE NOTE# 1	
MET-2	1/2 OZ COPPER	
	.016" 4403	
MET-3	1/2 OZ COPPER	0.062 0.067
	0.030" ± 0.002 ROGERS 4350 SEE NOTE# 1	
MET-4	1/2 OZ COPPER	

NOTES: UNLESS OTHERWISE SPECIFIED

1. MATERIAL: MULTILAYER. OVERALL STACKUP AS SHOWN. TYPE ROGERS 4350, HALF OUNCE COPPER BOTH SIDES.
2. FINISH: GOLD PLATE PER MIL-C-45204, TYPE III, GRADE A, 8 TO 40 MICROINCHES, OVER NICKEL PER QQ-N-290, 50 TO 100 MICROINCHES.
3. PLATED THRU HOLES: .001" MINIMUM WALL THICKNESS.
4. HOLE SIZES AND POSITIONS PER ARTWORK AND/OR DRILL FILE.
5. ALL HOLES TO BE LOCATED WITHIN ±.003" OF THE CENTER OF THE PAD OR OTHER TRUE POSITION.
6. FRONT TO BACK REGISTRATION ±.003" MAX
7. BOARD WARPAGE: .010" PER LINEAR INCH MAX
8. SILKSCREEN TOPSIDE ONLY WITH WHITE EPOXY INK
9. TOLERANCE ON PCB ROUTE IS ±.005"
10. PLATING THICKNESS .002" ± .0005 FOR MET-1 AND MET-4
11. SOLDERMASK: LPI SOLDERMASK TOPSIDE ONLY. COLOR: GREEN
REGISTRATION: ±.004 MAX
*** APPLY SOLDERMASK AS DESIGNED. ANY ALTERATIONS OF SOLDERMASK MUST FIRST BE APPROVED BY HITTITE MICROWAVE.
12. REMOVE METAL BURRS FROM EDGE OF PCB AFTER PANEL SEPERATION.
13. ARTWORK IS 1:1. VENDOR TO ADJUST FOR ETCH FACTOR.